

ABSTRACT

A method of printing high-quality high-density circuit pattern in a production of a ceramic thick-film printed circuit board. The method comprises forming a resin layer for prevention of sagging on a substrate before printing
5 the circuit pattern. The present invention provides conditions optimizing materials, thickness, surface roughness, printing conditions and firing conditions of the resin layer. According to the manufacturing method of the present invention, a ceramic thick-film printed circuit board densely printed with a satisfactory printed pattern and free of problems such as film exfoliation,
10 deformation of the pattern, pinholes and the like can readily be obtained.

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